

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|---|---------------------|
| 1 | 2 | substrate and (chip die IC) and ((flash-proof) (flash adj proof)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 10:27 |
| 2 | 1621 | 257/79-114.ccls. and substrate and (ic die chip) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:23 |
| 3 | 2 | ("20020089832").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:21 |
| 4 | 0 | huan-chien-ping.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:21 |
| 5 | 0 | huan-chienping.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:21 |
| 6 | 2 | huan-ping.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:21 |
| 7 | 875 | 257/81-82,91,88,99,100,103.ccls. and substrate and (ic die chip) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:25 |
| 8 | 415 | 257/81-82,91,88,99,100,103.ccls. and substrate and (ic die chip) and (encapsulat\$4 mold\$4 hous\$4 packag\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:47 |
| 9 | 1439 | 257/704-720,678-681,687-689.ccls. and substrate and (ic die chip) and (encapsulat\$4 mold\$4 hous\$4 packag\$4) and (heat adj (sink element plug spread\$4 plate)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:55 |
| 10 | 2 | ("6191360").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/17 12:55 |